

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-2 (Canceled).

Claim 3 (Currently Amended): A method for manufacturing a circuit device,
comprising:

mounting a plurality of electronic components on an insulation layer, the insulation layer stacked on a wiring layer of a wiring substrate, the electronic components each including an element to perform an electrical function and each having a bump electrode on one side and a pad electrode on the other side in such a manner that the bump electrode is buried into the insulation layer, the bump electrodes of the electronic components having substantially same height;

~~a bonding step of mounting an electronic component including an element for performing an electrical function on an insulation layer stacked on a wiring layer of a wiring substrate and pressing a terminal section~~ the pad electrode of each of the mounted electronic component ~~against the wiring substrate by a~~ components with a heater tool ~~whose pressing face has a given shape~~ having a planar pressing face to pattern a surface of the insulation layer after the pressing face, and pressing the electronic components into the insulation layer until the pad electrode reaches the surface of the insulation layer to electrically mechanically bond the electronic ~~component~~ components and the wiring layer together at the ~~terminal section~~ bump electrodes and then harden the insulation layer; and

~~a stacking step of electrically bonding another component to at least part of the terminal section bonded~~ pad electrodes pressed by the heater tool.

Application No. 09/961,172
Reply to Office Action of July 1, 2004

Claims 4-16 (Canceled).